

GaAs PIN Reflective SP4T Switch Chip, 2-26GHz

Performance characteristics

- Frequency range: 2-26GHz
- Insertion loss : 1.3dB typ.
- Isolation: 52 dB typ.
- P-1dB: See the table below
- 50Ω input / output
- 100% on-wafer testing
- Chip size: 2.77 x 2.27 x 0.1mm
- Silicon nitride passivation, scratch protection

Product Introduction

GSW410A is a GaAs PIN reflective single-pole four-throw switch chip with 50Ω matching at the input/output ends , a frequency range of 2 ~ 26 GHz , and -5V/+5V control. It has a built-in bias network and DC blocking capacitors , making it easy to use.

Use restriction parameter ¹	
Maximum input voltage	2.5V
Maximum input power	+37dBm CW
Operating temperature	-55 ~ +85°C
storage temperature	-65 ~ +150°C

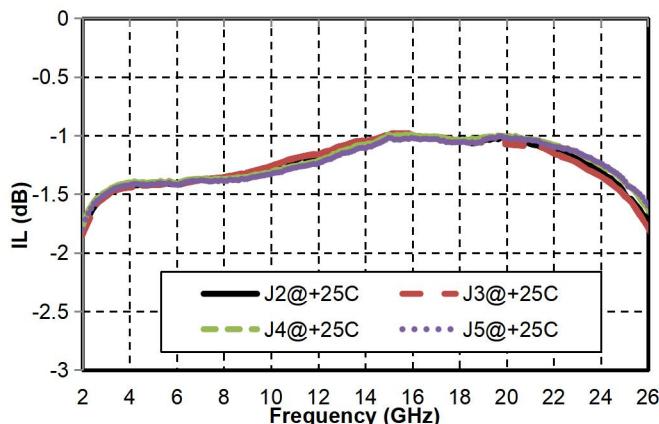
【1】 Exceeding any of these maximum limits may cause permanent damage.

Electrical performance parameters (TA ≈ +25°C)				
index	Minimum	Typical Value	Maximum	unit
Frequency Range		2-26		GHz
Insertion loss	-	1.2	-	dB
Isolation	-	52	-	dB
Input return loss	-	19	-	dB
Output return loss	-	11	-	dB
P-1dB	-	27.0@2GHz	-	dBm
		28.5@4GHz		dBm
		30.0@8GHz		dBm
		30.5@12GHz		dBm
		29.0@16GHz		dBm
		27.0@20GHz		dBm
Switching speed	-	20	-	ns

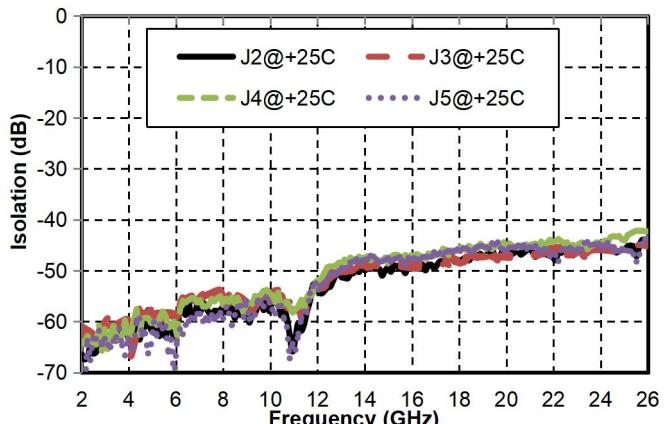
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Main index test curve

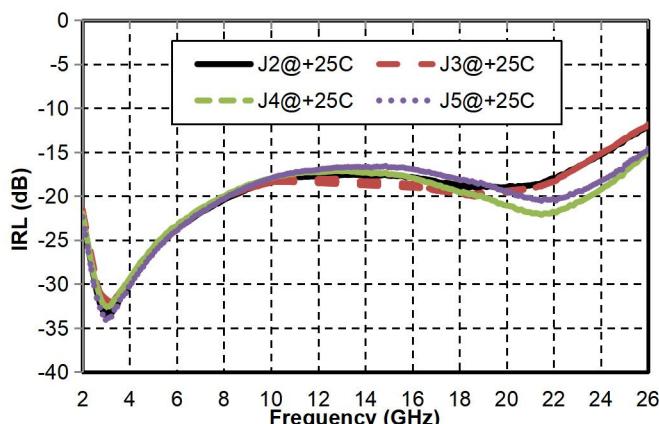
Insertion Loss vs. Operating Frequency



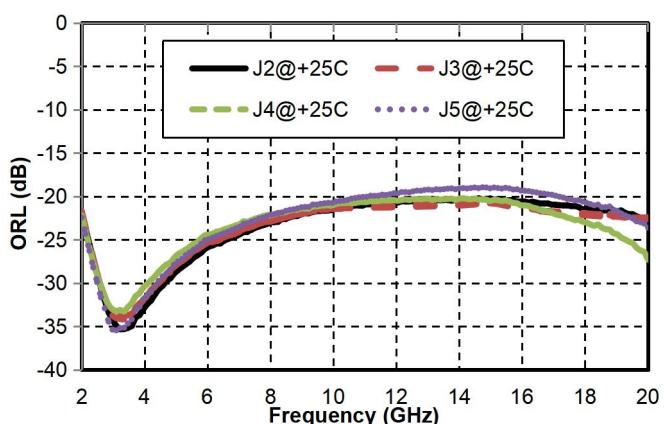
Isolation vs. Operating Frequency



Input Return Loss vs. Frequency



Output Return Loss vs. Frequency



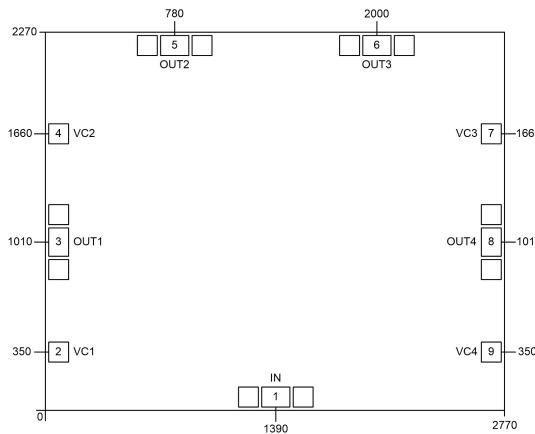
Typical Driver Connections

CONTROL LEVEL (DC CURRENT)				RF OUTPUT STATE			
VC1	VC2	VC3	VC4	J2-J1	J3-J1	J4-J1	J5-J1
-10mA	+ 15 mA	+ 15 mA	+ 15 mA	Low Loss	Isolation	Isolation	Isolation
+15mA	-10mA	+13mA	+15mA	Isolation	Low Loss	Isolation	Isolation
+15mA	+15mA	-10mA	+15mA	Isolation	Isolation	Low Loss	Isolation
+15mA	+ 15 mA	+ 15 mA	-10mA	Isolation	Isolation	Isolation	Low Loss

Note : V ≈ +2.6V, I ≈ +10mA; V ≈ -3.3V, I ≈ -15mA (including J1 end on-chip resistor RIN ≈ 50 ohm voltage divider)

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Appearance structure

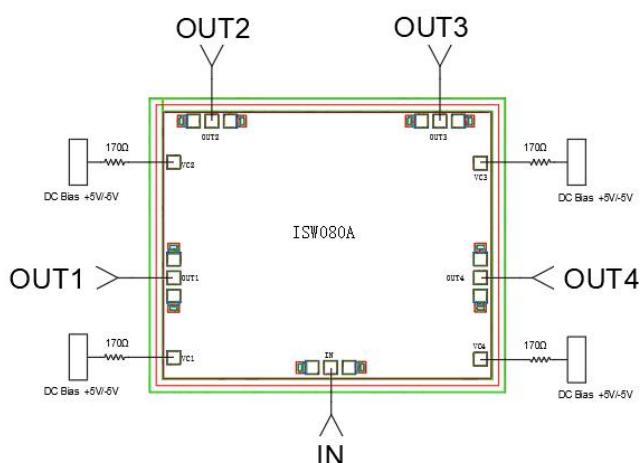


All units in the figure are micrometers

Bonding point definition

Bonding point number	Function Symbol	Functional Description
1 ,	IN(J1)	RF input signal terminal
3, 5, 6, 8	OUT1(J2), OUT2(J3), OUT3(J4), OUT4(J5)	RF output signal terminal
2, 4, 7, 9	VC1, VC2, VC3, VC4	Signal control terminal
Chip bottom	GND	The bottom of the chip needs to be well grounded to RF and DC

Recommended circuit diagram



+5V is connected in series with $R \approx 170$ ohm resistor, $V \approx +2.6V$, $I \approx + 15mA$. -5V is connected in series with $R \approx 170$ ohm resistor, $V \approx -3.3V$, $I \approx -10mA$.